Product / Package Information

Package	LFCSP -Sawn
Body Size (mm)	6 X 6 X0.85
Lead Count	40
Terminal Finish	NiPdAu
MS Number	MS012345B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.82E-02	93.70	937000	52.27	522739
Thermosets	Epoxy Resin	Proprietary	1.54E-03	3.00	30000	1.67	16737
Thermosets	Phenol Resin	Proprietary	1.54E-03	3.00	30000	1.67	16737
Other inorganic materials	Carbon Black	1333-86-4	1.54E-04	0.30	3000	0.17	1674
Subtotal			5.14E-02	100.00	1000000	55.79	557885

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.54 E-02	97.50	975000	38.36	383595
Copper & its alloys	Iron	7439-89-6	8.52 E-04	2.35	23500	0.92	9246
Copper & its alloys	Zinc	7440-66-6	4.35 E-05	0.12	1200	0.05	472
Copper & its alloys	Phosphorus	7723-14-0	1.09 E-05	0.03	300	0.01	118
Subtotal			3.63 E-02	100.00	1000000	39.34	393431

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	8.75 E-04	97.3	972697	0.95	9491
Precious metals	Palladium	7440-05-3	2.03 E-05	2.3	22621	0.02	221
Precious metals	Gold	7440-57-5	4.21 E-06	0.5	4683	0.005	46
Subtotal			8.99 E-04	100.00	1000000	0.98	9757

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.93 E-04	100.0	1000000	0.21	2098

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	2.86 E-03	100.0	1000000	3.11	31058

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.28 E-04	80.50	805000	0.46	4645
Other organic materials	Carbocyclic Acrylates	Proprietary	5.32 E-05	10.00	100000	0.06	577
Other organic materials	Bismaleimide resin	Proprietary	1.60 E-05	3.00	30000	0.02	173
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	1.60 E-05	3.00	30000	0.02	173
Others	Additive	Proprietary	1.60 E-05	3.00	30000	0.02	173
Other organic materials	Dicumyl peroxide	80-43-3	2.66 E-06	0.50	5000	0.003	29
Subtotal			5.32 E-04	100.0	1000000	0.58	5770

	Weight (g)	Percentage (%)	PPM
Package Totals	**9.22 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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